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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

10/019696

APPL NUM 10019696	FILING DATE 06/20/2002	CLASS 257	SUBCLASS 679	GAU 2811	EXAMINER T. T. Vu
**APPLICANTS: Finn David; Rietzler Manfred;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/DE00/01396 05/04/2000					
** FOREIGN APPLICATIONS VERIFIED: GERMANY 19920593.0 05/05/1999					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials <u>av</u>				ATTORNEY DOCKET NO 70357	
TITLE : Chip carrier a chip module and method of manufacturing the chip module					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436 (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs. Drawg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
		Application Examiner	
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